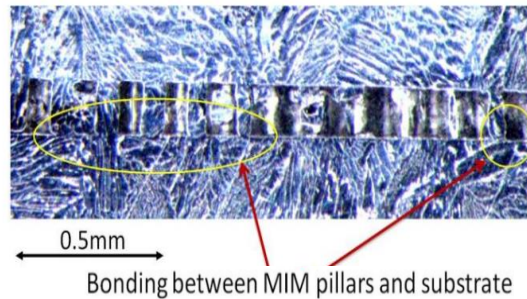


Method for Bonding Metal Injection Molded Parts to Conventional Substrate Using Controlled Surface Microstructure

Description:

This technology features a novel Metal Injection Molded (MIM) manufacturing method which allows for the formation of intricate device geometries and attachment of dissimilar materials. By applying a controlled, deformable microstructure to the MIM part, the MIM part is given the ability to shrink while bonding to the substrate. This bonding method features a reduced susceptibility to cracking, improved bond shear strength over comparable methods, and feasible integration into current manufacturing practices.



Applications:

- Automotive parts
- Biomedical Surgical Tools

Benefits:

- Competitive bonding strength similar to resistance welding
- Flexibility of materials
- Conventional manufacturing techniques and equipment

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Protection Status:	Patent application filed
Licensing Status:	Available for licensing
Additional Terms:	Fabrication, Manufacturing, Injection Molding
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